

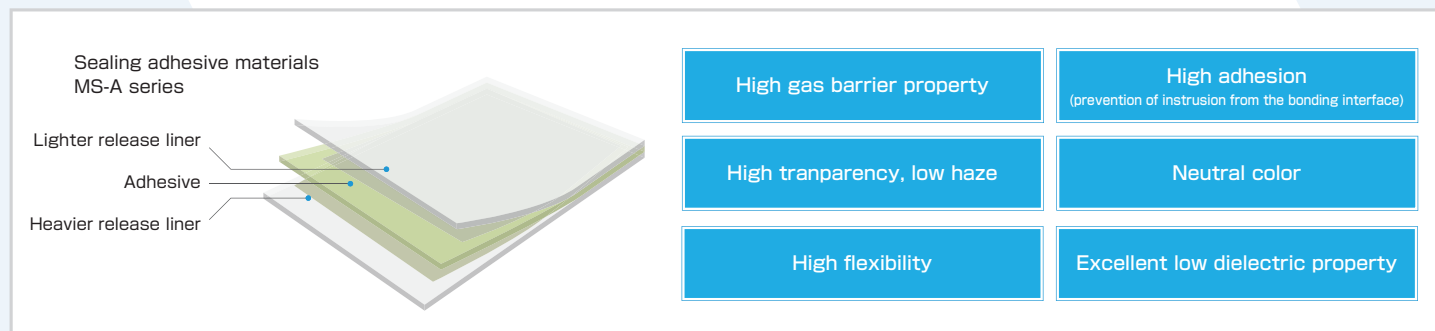
Gas Barrier Encapsulation Materials MS series

Gas Barrier Encapsulation Materials MS-A

Relates to our sealing adhesive materials (MS-A) having excellent durability and adhesion. These materials contribute as a high reliable sealing adhesive to a lower weight and greater flexibility in devices, including organic EL devices (displays and lighting), organic solar cells, and electronic paper.



Composition



Product Line-up

Name	MS-A3010P		MS-A3010Q		Development product	
Adhesive Type	Thermal curing					
	High modulus		Low modulus		Low dielectric constant	
Structure	Lighter release liner	38μm	Lighter release liner	38μm	Lighter release liner	38μm
	Adhesive	10μm	Adhesive	10μm	Adhesive	15μm
	Heavier release liner	75μm	Heavier release liner	75μm	Heavier release liner	75μm
Curing condition	90-100℃ - 1 hour		90-100℃ - 1 hour		160℃ - 1 hour	
T.t.[%] ^{*1}	> 90		> 90		> 90	
Haze(%) ^{*2}	< 1		< 1		< 1	
b* ^{*3}	< 0.5		< 0.5		< 1	
Adhesion to glass [N/25 mm] ^{*4}	30		10		-	
WVTR (g・m ⁻² ・day ⁻¹) ^{*5}	30		50		-	
Dielectric constant	DK:2.5, Df:0.009@1GHz		Dk:3.0, Df:0.03@1GHz		Dk:2.4, Df:0.002@1GHz Dk:2.2, Df:0.002@10GHz	

*1 Measuring method : JIS K 7136

*2 Measuring method : JIS K7361-1

*3 Measuring method : JIS Z8729

*4 Measuring method : JIS Z0237

*5 Measuring method : Lissi method ASTM E398 -03, Test environment: 40°C, 90%RH(Thickness 100μm)



LINTEC Corporation *Linking your dreams*

● HEAD OFFICE 23-23 Honcho, Itabashi-ku, Tokyo 173-0001, Japan

Optical products Operations

8th Fl., Bunkyo Garden Gate Tower, 1-1-1 Koishikawa,
Bunkyo-ku, Tokyo 112-0002, Japan
TEL. +81-3-3868-7758 FAX. +81-3-3868-7759

www.opteria-global.com/en